

# STP2NC60

## STP2NC60FP

### N-CHANNEL 600V - 7Ω - 1.9A - TO-220/TO-220FP

### PowerMesh™II MOSFET

TYPE	V <sub>DSS</sub>	R <sub>D(on)</sub>	I <sub>D</sub>
STP2NC60	600 V	< 8 Ω	1.9 A
STP2NC60FP	600 V	< 8 Ω	1.9 A

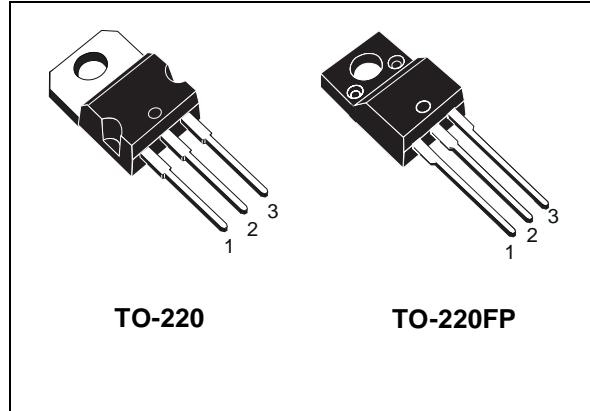
- TYPICAL R<sub>D(on)</sub> = 7 Ω
- EXTREMELY HIGH dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- NEW HIGH VOLTAGE BENCHMARK
- GATE CHARGE MINIMIZED

#### DESCRIPTION

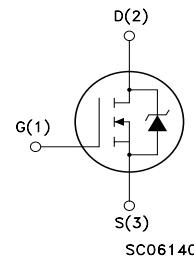
The PowerMESH™II is the evolution of the first generation of MESH OVERLAY™. The layout refinements introduced greatly improve the Ron\*area figure of merit while keeping the device at the leading edge for what concerns switching speed, gate charge and ruggedness.

#### APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- DC-AC CONVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLIES AND MOTOR DRIVER



INTERNAL SCHEMATIC DIAGRAM



SC06140

#### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value		Unit
		STP2NC60	STP2NC60FP	
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	600	600	V
V <sub>DGR</sub>	Drain-gate Voltage (R <sub>GS</sub> = 20 kΩ)	600	600	V
V <sub>GS</sub>	Gate- source Voltage	±30	±30	V
I <sub>D</sub>	Drain Current (continuos) at T <sub>C</sub> = 25°C	1.9	1.9 (*)	A
I <sub>D</sub>	Drain Current (continuos) at T <sub>C</sub> = 100°C	1.2	1.2 (*)	A
I <sub>DM</sub> (1)	Drain Current (pulsed)	7.4	7.4 (*)	A
P <sub>TOT</sub>	Total Dissipation at T <sub>C</sub> = 25°C	70	30	W
	Derating Factor	0.56	0.24	W/°C
dv/dt	Peak Diode Recovery voltage slope	3.5		V/ns
V <sub>ISO</sub>	Insulation Withstand Voltage (DC)	-	2000	V
T <sub>stg</sub>	Storage Temperature	-60 to 150		°C
T <sub>j</sub>	Max. Operating Junction Temperature	150		°C

(•)Pulse width limited by safe operating area

(1)I<sub>SD</sub> ≤ 1.9A, di/dt ≤ 100A/μs, V<sub>DD</sub> ≤ V<sub>(BR)DSS</sub>, T<sub>j</sub> ≤ T<sub>JMAX</sub>

(\*) Limited only by Maximum Temperature Allowed

## STP2NC60/STP2NC60FP

### THERMAL DATA

		TO-220	TO-220FP	
Rthj-case	Thermal Resistance Junction-case Max	1.76	4.125	°C/W
Rthj-amb	Thermal Resistance Junction-ambient Max	62.5		°C/W
Rthc-sink	Thermal Resistance Case-sink Typ	0.5		°C/W
T <sub>I</sub>	Maximum Lead Temperature For Soldering Purpose	300		°C

### AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I <sub>AR</sub>	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T <sub>j</sub> max)	1.9	A
E <sub>AS</sub>	Single Pulse Avalanche Energy (starting T <sub>j</sub> = 25 °C, I <sub>D</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 50 V)	80	mJ

### ELECTRICAL CHARACTERISTICS (TCASE = 25 °C UNLESS OTHERWISE SPECIFIED) OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	I <sub>D</sub> = 250 μA, V <sub>GS</sub> = 0	600			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max Rating V <sub>DS</sub> = Max Rating, T <sub>C</sub> = 125 °C			1 10	μA μA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ±30V			±100	nA

### ON (1)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2	3	4	V
R <sub>DSS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 0.7 A		7	8	Ω
I <sub>D(on)</sub>	On State Drain Current	V <sub>DS</sub> > I <sub>D(on)</sub> x R <sub>DSS(on)max</sub> , V <sub>GS</sub> = 10V	1.9			A

### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g <sub>fs</sub> (1)	Forward Transconductance	V <sub>DS</sub> > I <sub>D(on)</sub> x R <sub>DSS(on)max</sub> , I <sub>D</sub> = 0.7A		1.25		S
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25V, f = 1 MHz, V <sub>GS</sub> = 0		160		pF
C <sub>oss</sub>	Output Capacitance			26		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			3.8		pF

**ELECTRICAL CHARACTERISTICS (CONTINUED)****SWITCHING ON**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 300V, I_D = 0.7 A$ $R_G = 4.7\Omega, V_{GS} = 10V$ (see test circuit, Figure 3)		8		ns
$t_r$	Rise Time			8		ns
$Q_g$	Total Gate Charge	$V_{DD} = 480V, I_D = 1.4 A$ , $V_{GS} = 10V$		8.5	11.5	nC
$Q_{gs}$	Gate-Source Charge			2.8		nC
$Q_{gd}$	Gate-Drain Charge			2.8		nC

**SWITCHING OFF**

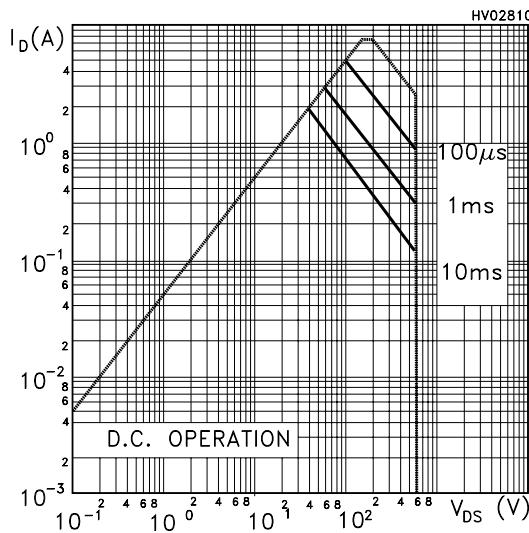
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{r(Voff)}$	Off-voltage Rise Time	$V_{DD} = 480V, I_D = 1.4 A$ , $R_G = 4.7\Omega, V_{GS} = 10V$		25		ns
$t_f$	Fall Time			9		ns
$t_c$	Cross-over Time			34		ns

**SOURCE DRAIN DIODE**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain Current				1.9	A
$I_{SDM}$ (2)	Source-drain Current (pulsed)				7.4	A
$V_{SD}$ (1)	Forward On Voltage	$I_{SD} = 1.4 A, V_{GS} = 0$			1.6	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = 1.4 A, di/dt = 100A/\mu s$ , $V_{DD} = 100V, T_j = 150^\circ C$		500		ns
$Q_{rr}$	Reverse Recovery Charge			950		nC
$I_{RRM}$	Reverse Recovery Current			3.8		A

Note: 1. Pulsed: Pulse duration = 300  $\mu s$ , duty cycle 1.5 %.

2. Pulse width limited by safe operating area.

**Safe Operating Area for TO-220****Safe Operating Area for TO-220FP**